



SOT1081-1

plastic extremely thin small outline package; no leads; 10 terminals; UTLP based; body 1 x 1.7 x 0.5 mm

8 June 2016

Package information

1. Package summary

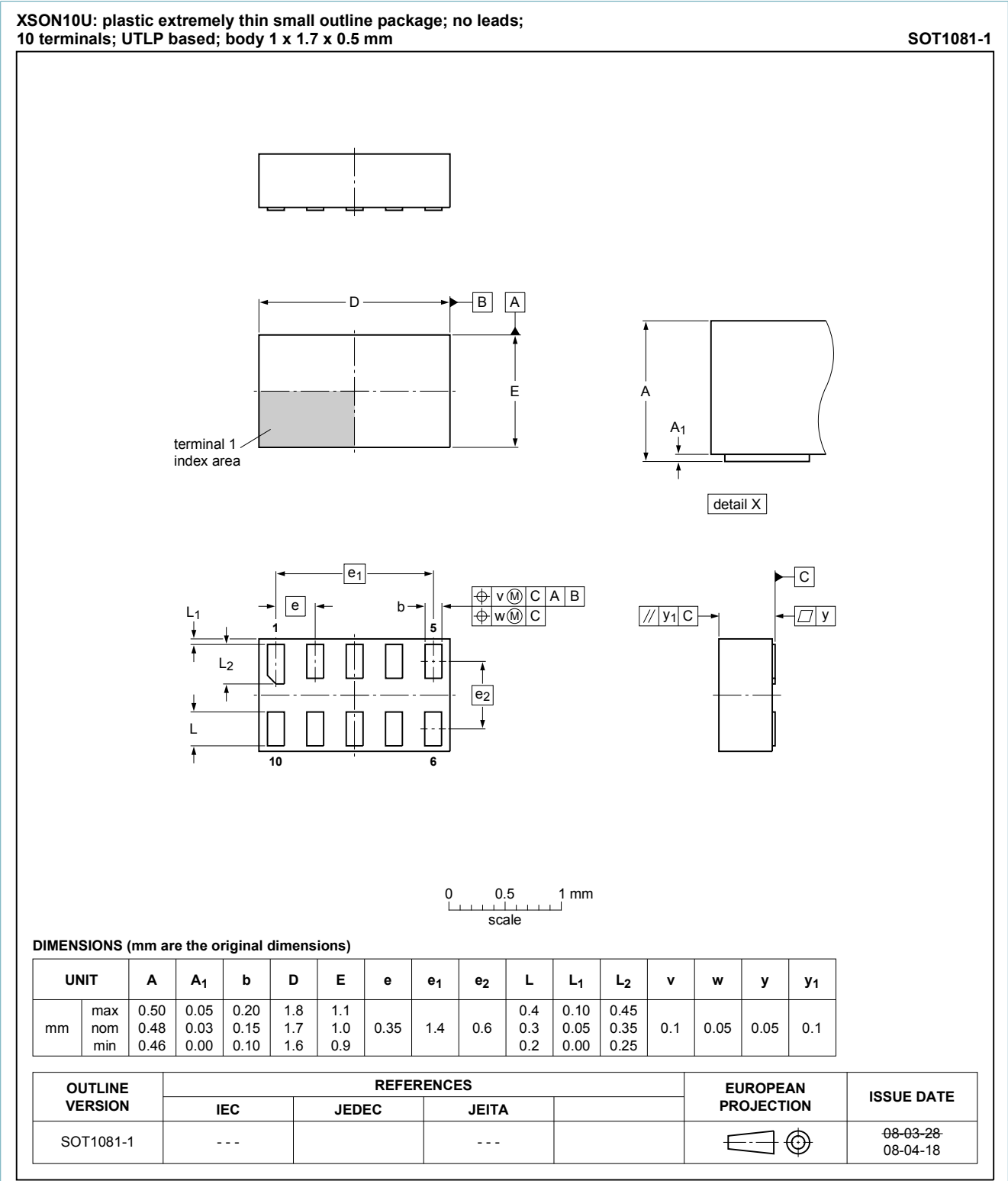
Terminal position code	D (double)
Package type descriptive code	XSON10U
Package type industry code	XSON10U
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package body material type	P (plastic)
IEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	18-4-2008

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.6	-	1.7	1.8	mm
E	package width		0.9	-	1	1.1	mm
A	seated height		0.46	-	0.48	0.5	mm
A ₂	package height		-	-	-	-	
e	nominal pitch		-	-	0.35	-	mm
n ₂	actual quantity of termination		-	-	10	-	



2. Package outline



3. Soldering

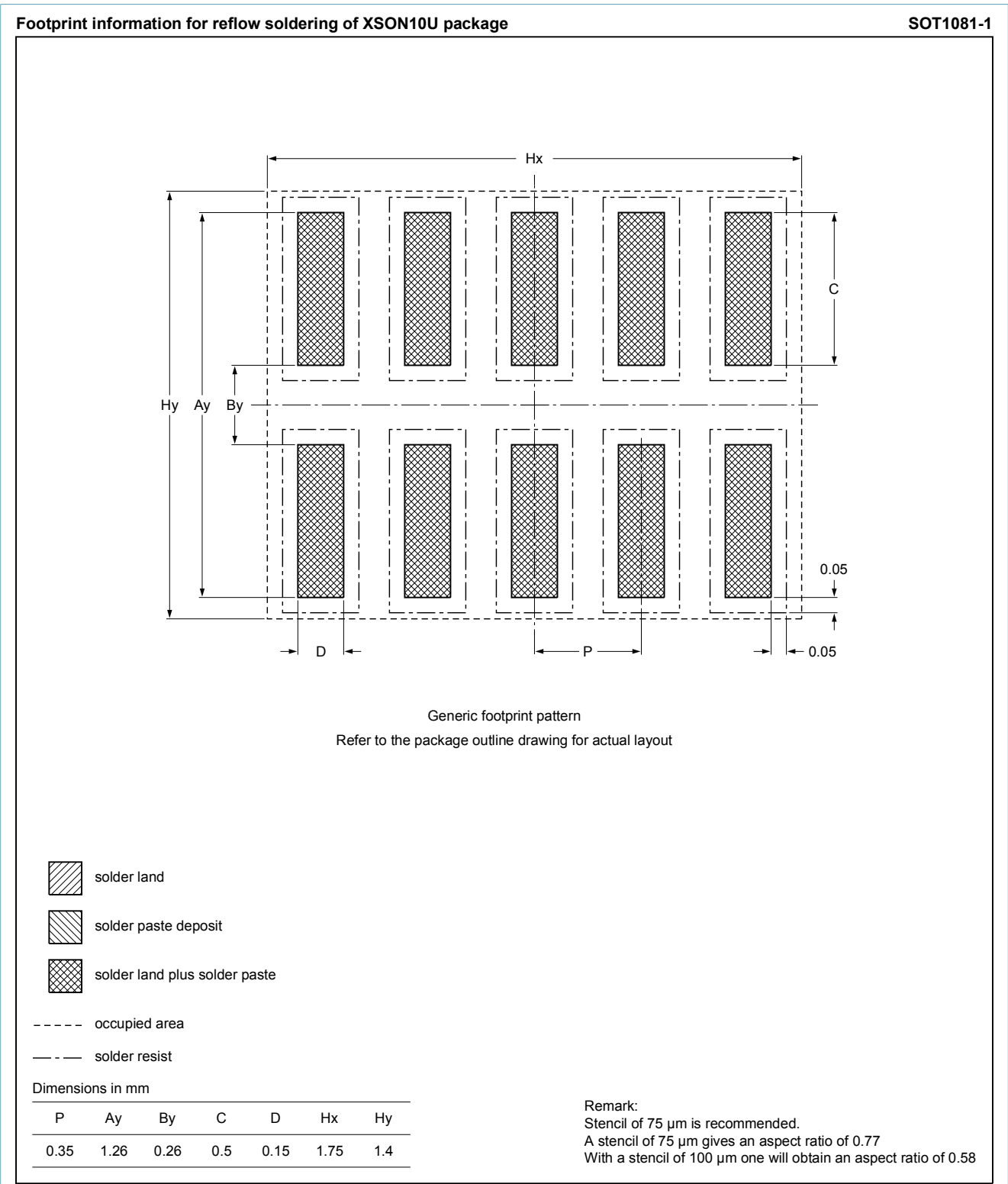


Fig. 2. Reflow soldering footprint for XSON10U (SOT1081-1)

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4. Legal information

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